

IEEE

MARCH/APRIL 2016

# Design & Test



ALEXANDER TORRES 2016

## Advances in 3-D Integrated Circuits, Systems, and CAD Tools—Part 2

- Delay Characterization and Testing of Arbitrary Multiple-Pin Interconnects
- High-Frequency Temperature-Dependent Through-Silicon-Via (TSV) Model and High-Speed Channel Performance for 3-D ICs
- Configurable Cubical Redundancy Schemes for Channel-Based 3-D DRAM Yield Improvement
  - Thermoelectric Codesign of 3-D CPUs and Embedded Microfluidic Pin-Fin Heatsinks

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March/April 2016  
Volume 33 Number 2

Copublished by the IEEE Council  
on Electronic Design Automation,  
the IEEE Circuits and Systems  
Society, the IEEE Solid-State  
Circuits Society, and the Test  
Technology Technical Council

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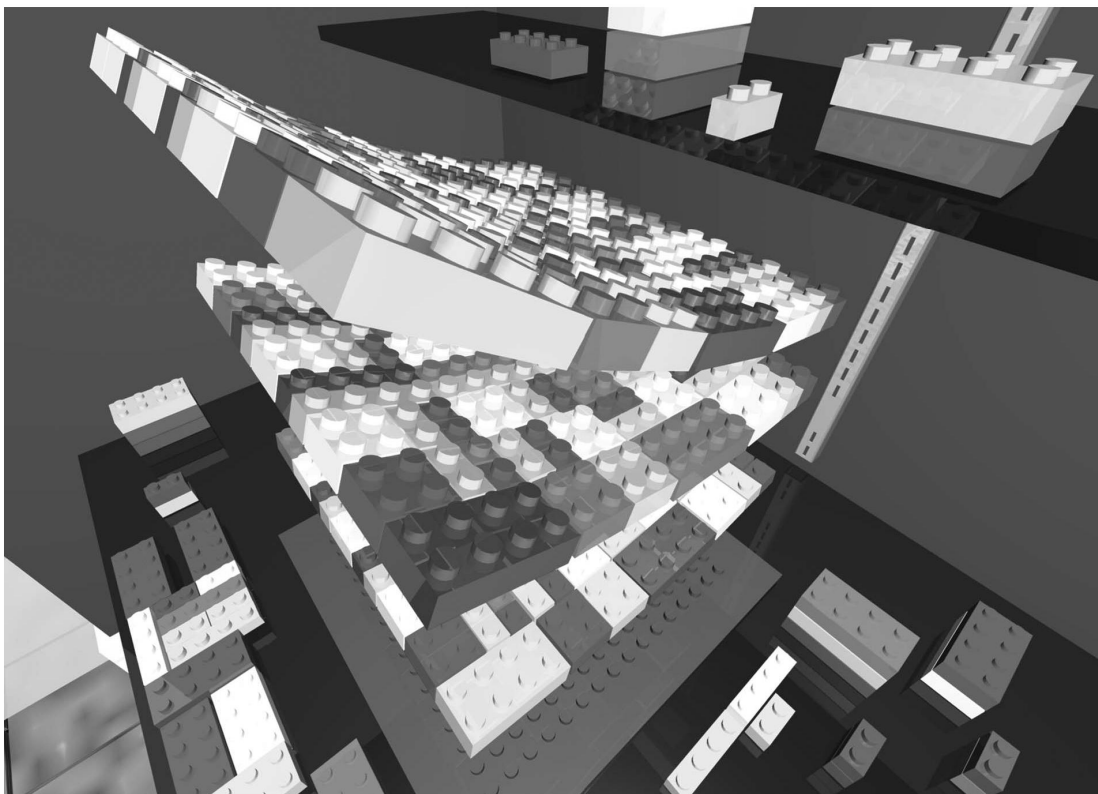
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Cover design by Alexander Torres

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